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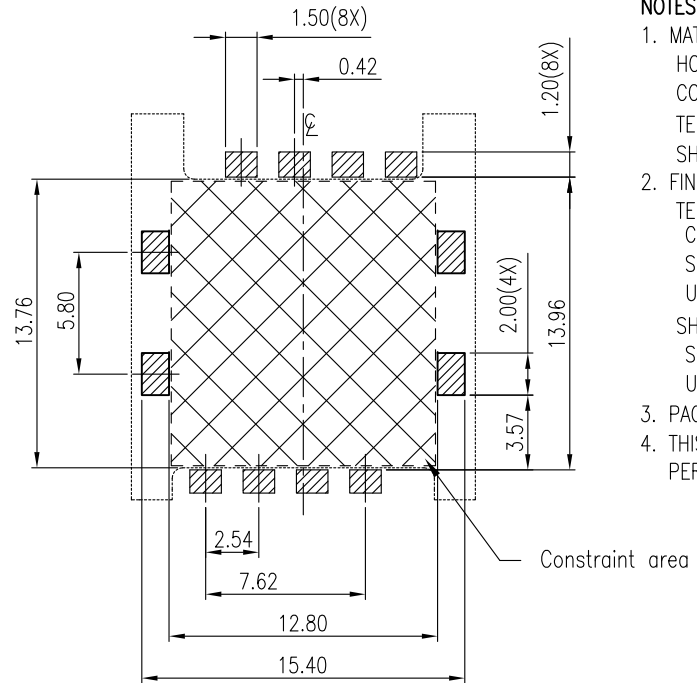
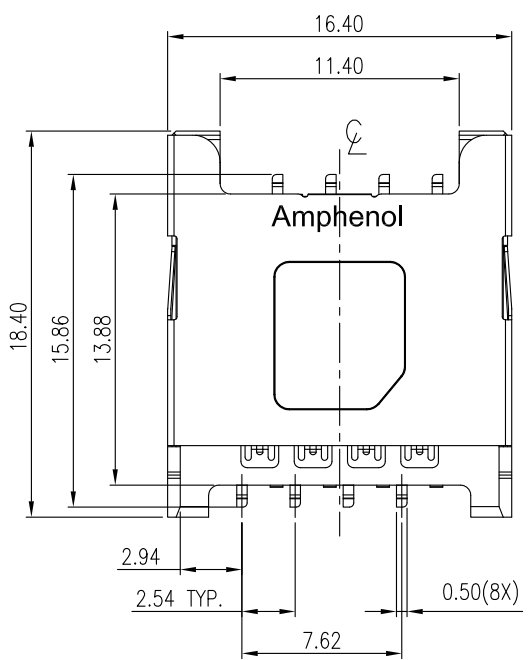
The marking on this product doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2002/95/EC for RoHS compliant.

**PRELIMINARY RELEASE
SUBJECT TO CHANGE**

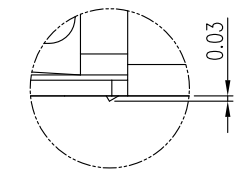
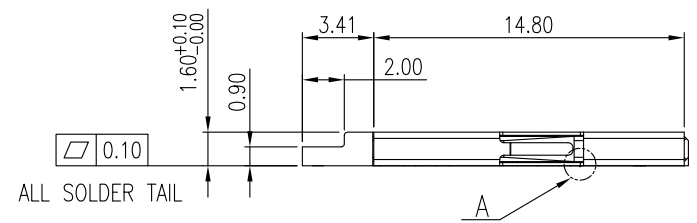
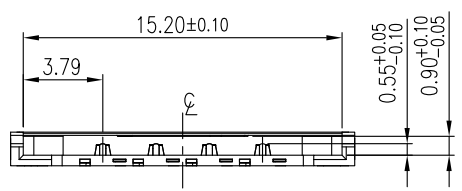
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
AX1		NON-RELEASE REVISION	05/12/2010	Roger Tsai

NOTES:

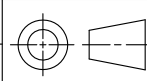
- MATERIAL:
 - HOUSING: HIGH TEMPERATURE THERMAL PLASTIC, UL94V-0, COLOR: BLACK.
 - COVER: HIGH TEMPERATURE THERMAL PLASTIC, UL94V-0, COLOR: BLACK.
 - TERMINAL: COPPER ALLOY.
 - SHELL: COPPER ALLOY.
- FINISH:
 - TERMINAL:
 - CONTACT AREA: GOLD PLATING;
 - SOLDERING AREA: TIN PLATING 100 μ" THICKNESS MIN.;
 - UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
 - SHELL:
 - SOLDERING AREA: TIN PLATING 100 μ" THICKNESS MIN.;
 - UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
- PACKING IS PER AMTA PACKING SPECIFICATION PKS-0001.
- THIS PRODUCT DOESN'T CONTAIN ENVIRONMENTAL HAZARDOUS PER DIRECTIVE 2002/95/EC FOR RoHS COMPLIANT.



RECOMMENDED PCB LAYOUT
TOLERANCE ±0.05mm



Working Position Max.
DETAIL A
5:1

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol®		
X.		DRAWN	Roger Tsai	05/12/2010	SIM CARD CONNECTOR, 8 POS HEIGHT:1.60 MM		Amphenol Corporation Amphenol Taiwan Corporation		
X.X	±0.30	CHECKED	Chenny Yeh	05/12/2010					
X.XX	±0.20	APPROVED	Roger Tsai	05/12/2010	 UNIT mm SIZE A3 SCALE NA SHEET 1 OF 1		PART No. G85A10082144EU		
X.XXX	±0.10	DWG TYPE	CUST DWG	PROJECT CODE			OTHER	DWG No. G85A10082144EU REV. AX1	
ANGULAR	±1°								
UNLESS OTHERWISE SPECIFIED									